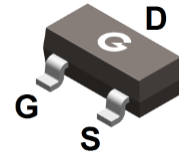
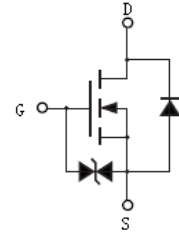


Features

- Advanced trench technology
- Integrated ESD protection diode
- Fast switching speed
- HBM: AEC-Q101-001: H1C (JESD22-A114-B: 1C)
- RoHS compliant with Halogen-free
- Qualified to AEC-Q101 Standards

HF



SOT-23

Mechanical Data

- Case: SOT-23
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TBL03N06KC	SOT-23	3000 pcs / Tape & Reel	03N06K

Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate -Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$)	I_D	3	A
Continuous Drain Current ($T_A = 25^\circ\text{C}$) ^{*1}		2.6	A
Continuous Drain Current ($T_A = 70^\circ\text{C}$) ^{*1}		2.1	A
Pulsed Drain Current ($t_p = 10\mu\text{s}$, $T_A = 25^\circ\text{C}$)	I_{DM}	20	A
Single Pulse Avalanche Energy ^{*3}	E_{AS}	1	mJ
Power Dissipation ($T_A = 25^\circ\text{C}$) ^{*1}	P_D	1.5	W
Operating Junction Temperature Range	T_J	$-55 \sim +150$	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	50	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air ^{*1}	$R_{\theta JA}$	-	-	83	$^\circ\text{C/W}$

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48V, V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	-	-	±10	μA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance *2	V _{GS} = 10V, I _D = 1A	-	85	100	mΩ
		V _{GS} = 4.5V, I _D = 1A	-	95	120	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.6	2.5	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	7.6	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V V _{DS} = 30V f = 1.0MHz	-	325	-	pF
C _{OSS}	Output Capacitance		-	21	-	
C _{RSS}	Reverse Transfer Capacitance		-	16	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time *4	V _{DD} = 30V, V _{GS} = 10V I _D = 1A R _G = 25Ω	-	6	-	ns
t _r	Turn-on Rise Time *4		-	5	-	
t _{d(OFF)}	Turn-Off Delay Time *4		-	25	-	
t _f	Turn-Off Fall Time *4		-	15	-	
Q _G	Total Gate-Charge(V _{GS} = 10V)	V _{DD} = 48V V _{GS} = 4.5V I _D = 1A	-	9.5	-	nC
	Total Gate-Charge(V _{GS} = 4.5V)			4.7		
Q _{GS}	Gate to Source Charge		-	1.47	-	
Q _{GD}	Gate to Drain (Miller) Charge		-	1.44	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage *2	I _{SD} = 1A, V _{GS} = 0V	-	0.8	1.3	V
t _{rr}	Reverse Recovery Time	I _F = 1A, V _{GS} = 0V	-	15	-	ns
Q _{rr}	Reverse Recovery Charge	d _I /d _t = 100A/μs	-	6.5	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating. The test condition is $V_{DD} = 30V, V_{GS} = 10V, L = 0.1mH$
4. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

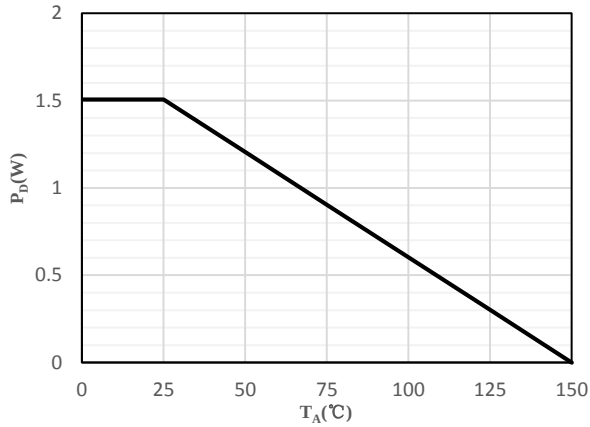


Fig 1 Power Dissipation

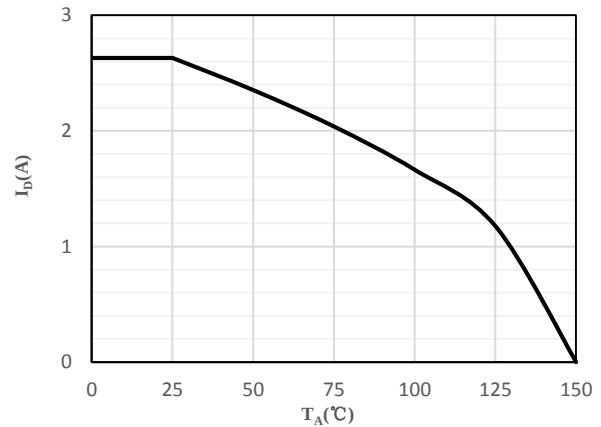


Fig 2 Drain Current

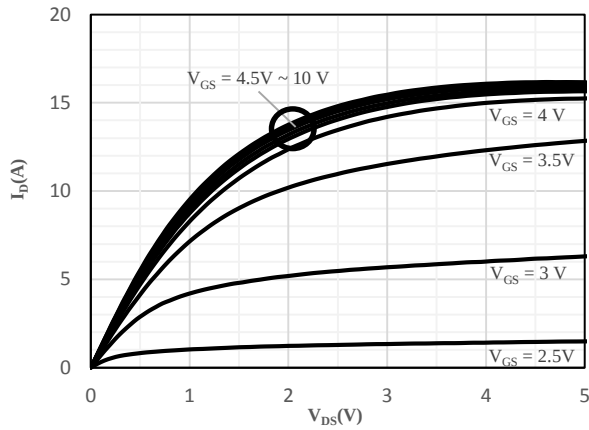


Fig 3 Typical Output Characteristics

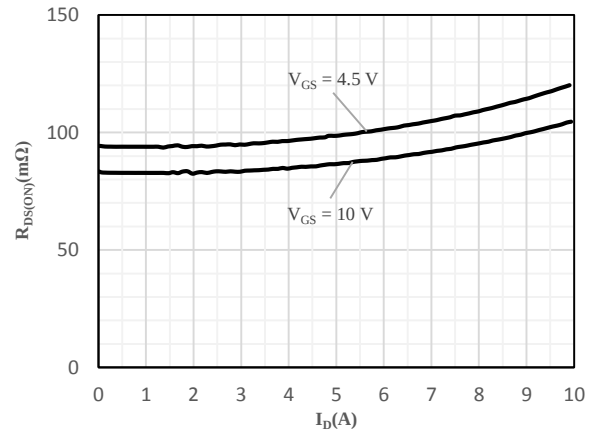


Fig 4 On-Resistance vs. Drain Current
and Gate Voltage

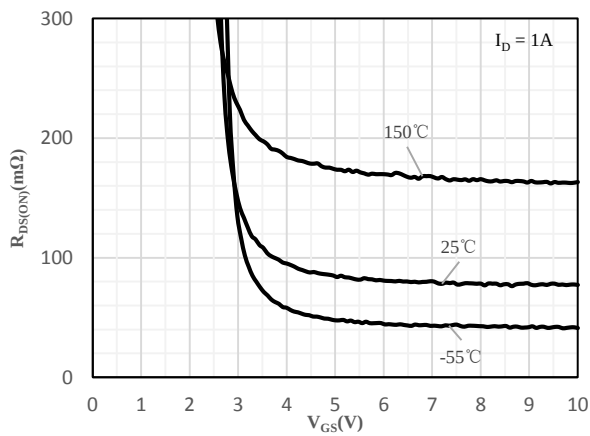


Fig 5 On-Resistance vs. Gate-Source Voltage

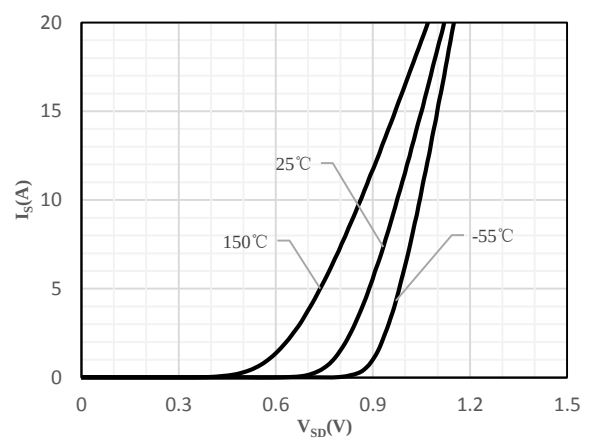


Fig 6 Body-Diode Characteristics

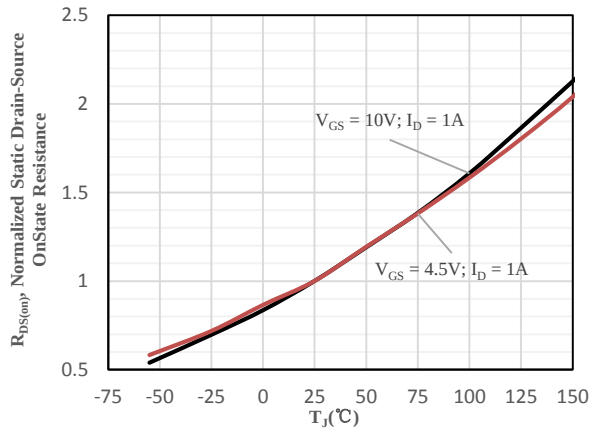


Fig 7 Normalized On-Resistance vs. Junction Temperature

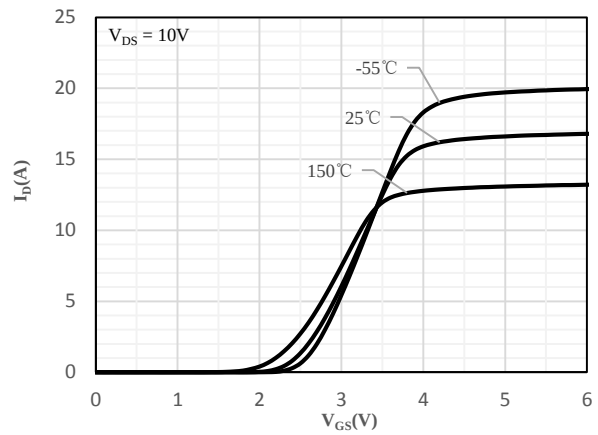


Fig 8 Transfer Characteristics

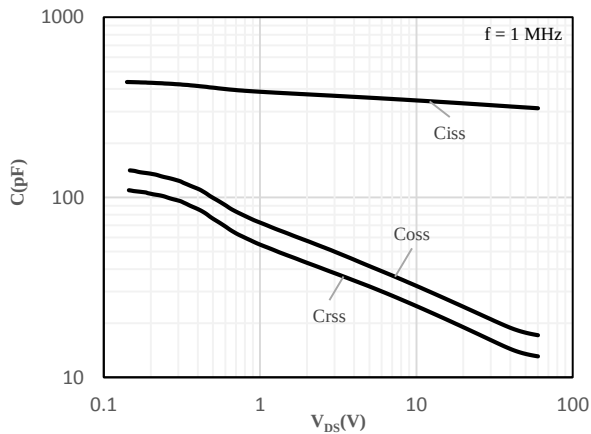


Fig 9 Capacitance Characteristics

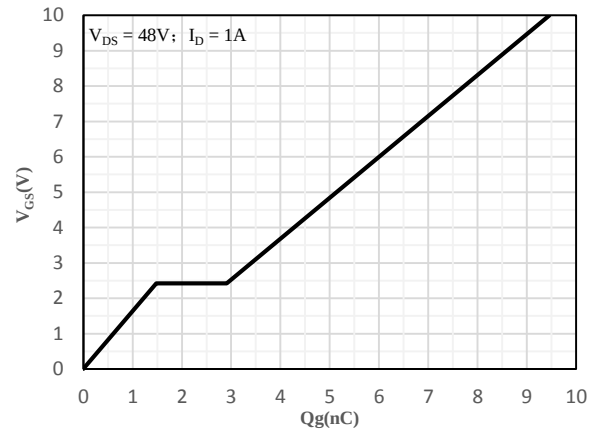


Fig 10 Gate-Charge Characteristics

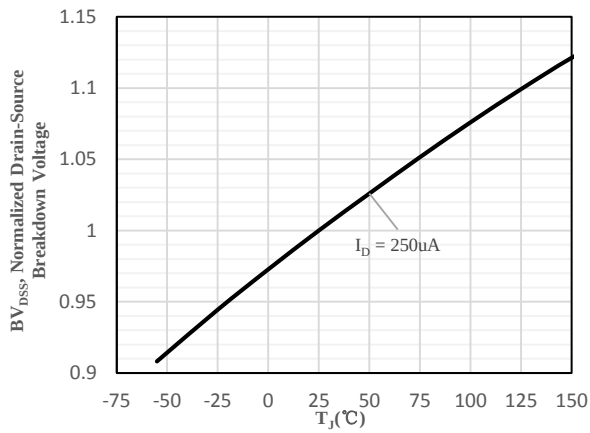


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

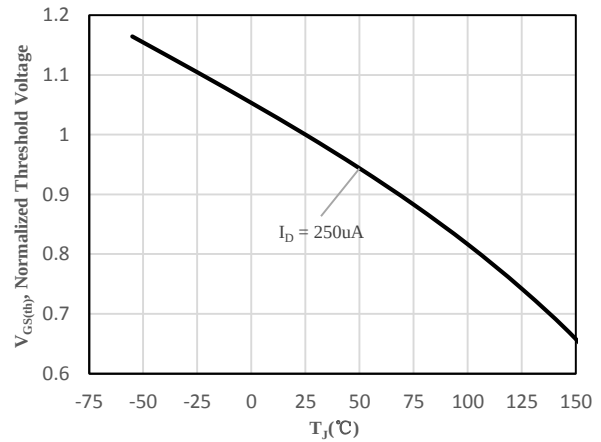
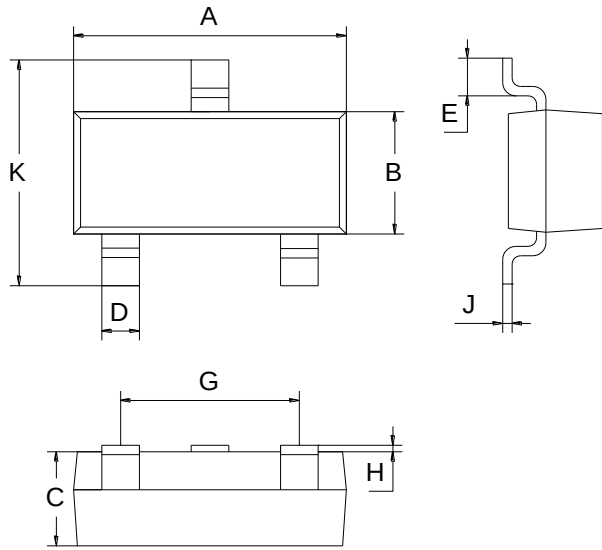


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

Package Outline Dimensions (Unit: mm)



SOT-23		
Dimension	Min.	Max.
A	2.70	3.10
B	1.10	1.50
C	0.90	1.10
D	0.30	0.50
E	0.35	0.48
G	1.80	2.00
H	0.02	0.10
J	0.05	0.15
K	2.20	2.60

Mounting Pad Layout (Unit: mm)

SOT-23

